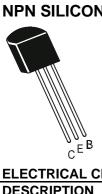


NPN SILICON PLANAR EPITAXIAL RF TRANSISTORS	BF494
	BF495
	TO-92
	Plastic Package
CEB	

High Voltage Video Transistors

ABSOLUTE MAXIMUM RATINGS(Ta=25°C unless specified otherwise)

DESCRIPTION	SYMBOL		Value		UNITS
Collector Emitter Voltage	V_{CEO}		20		V
Collector Base Voltage	V _{CBO}		30		V
Emitter Base Voltage	V _{EBO}		5		V
Collector Current (DC)	Ι _C		30		mA
Collector Current(peak value)	I _{CM}		30		mA
Total Power dissipation up to	P _{tot}		300		mW
Tamb = 25°C					mW/ºC
Operating And Storage Junction	T _j , T _{stg}		-55 to +150		°C
Temperature Range					
THERMAL RESISTANCE					
	D		400		
Junction to ambient	$R_{th(j-a)}$		420		K/W
ELECTRICAL CHARACTERISTICS (Ta=25⁰C Unle	ss Otherwise Specifie	d)		
,	14-10 0 01110				
DESCRIPTION	SYMBOL	TEST CONDITION	Min	Max	UNITS
	SYMBOL I _{CBO}	•	1	Max 500	UNITS nA
Collector Cut- off Current		TEST CONDITION	1		
Collector Cut- off Current	I _{CBO}	TEST CONDITION V _{CB} =20V,I _E =0	1		
Collector Cut- off Current Collector Cut - off Current	I _{CBO}	TEST CONDITION $V_{CB}=20V,I_{E}=0$ $V_{CB}=20V,I_{E}=0$	1	500	nA
Collector Cut- off Current Collector Cut - off Current EmitterCut off Current	I _{CBO} I _{CBO} I _{EBO}	TEST CONDITION $V_{CB}=20V,I_E=0$ $V_{CB}=20V,I_E=0$ Ta =150 °C	1	500 4.0	nA μA
Collector Cut- off Current Collector Cut - off Current EmitterCut off Current Base Emitter Voltage	I _{сво} I _{сво}	TEST CONDITION $V_{CB}=20V,I_E=0$ $V_{CB}=20V,I_E=0$ Ta = 150 °C $V_{EB}=4V, I_C=0$	Min	500 4.0 500	nA μA nA
Collector Cut- off Current Collector Cut - off Current EmitterCut off Current Base Emitter Voltage	I _{CBO} I _{CBO} I _{EBO} V _{BE(ON)}	TEST CONDITION $V_{CB}=20V,I_E=0$ $V_{CB}=20V,I_E=0$ Ta = 150 °C $V_{EB}=4V, I_C=0$	Min	500 4.0 500	nA μA nA
Collector Cut- off Current Collector Cut - off Current EmitterCut off Current Base Emitter Voltage DC Current Gain	I _{CBO} I _{CBO} I _{EBO} V _{BE(ON)} 94 h _{FE *}	TEST CONDITION $V_{CB}=20V, I_E=0$ $V_{CB}=20V, I_E=0$ Ta =150 °C $V_{EB}=4V, I_C=0$ $V_{CE}=10V, I_C=1mA$	Min 0.65	500 4.0 500 0.74	nA μA nA
Collector Cut- off Current Collector Cut - off Current EmitterCut off Current Base Emitter Voltage DC Current Gain BF4	I _{CBO} I _{CBO} V _{BE(ON)} 94 h _{FE *} 4A	TEST CONDITION $V_{CB}=20V, I_E=0$ $V_{CB}=20V, I_E=0$ Ta =150 °C $V_{EB}=4V, I_C=0$ $V_{CE}=10V, I_C=1mA$	Min 0.65 67	500 4.0 500 0.74 221	nA μA nA
Collector Cut- off Current Collector Cut - off Current EmitterCut off Current Base Emitter Voltage DC Current Gain BF494 BF494 BF494 BF494	I _{CBO} I _{CBO} V _{BE(ON)} 94 h _{FE} - 48 95	TEST CONDITION $V_{CB}=20V, I_E=0$ $V_{CB}=20V, I_E=0$ Ta =150 °C $V_{EB}=4V, I_C=0$ $V_{CE}=10V, I_C=1mA$	Min 0.65 67 200 110 35	500 4.0 500 0.74 221 500 215 125	nA μA nA
Collector Cut - off Current EmitterCut off Current Base Emitter Voltage DC Current Gain BF494 BF494	I _{CBO} I _{CBO} V _{BE(ON)} 94 h _{FE} - 4A 4B 95 5C	TEST CONDITION $V_{CB}=20V, I_E=0$ $V_{CB}=20V, I_E=0$ Ta =150 °C $V_{EB}=4V, I_C=0$ $V_{CE}=10V, I_C=1mA$	Min 0.65 67 200 110	500 4.0 500 0.74 221 500 215	nA μA nA



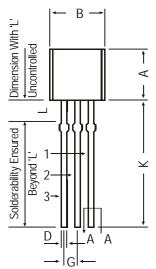
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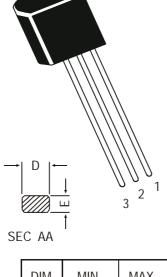
TO-92 Plastic Package

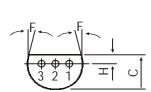
DESCRIPTION	SYMBOL	TEST CONDITION	Min	Max	UNITS
DYNAMIC CHARACTERISTICS					
Transition Frequency	f _T	$I_C=1mA$, $V_{CE}=10V$	120		MHz
Feedback Capacitance	C _{re}	V _{CE} =10V, I _C =1mA f=4.5MHz		1.0	pF

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TO-92 Plastic Package







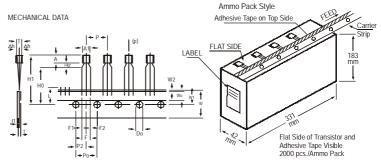
PIN CONFIGURATION

- 1. BASE
- 2. EMITTER
- 3. COLLECTOR

DIM	MIN.	MAX.			
А	4.32	5.33			
В	4.45	5.20			
С	3.18	4.19			
D	0.41	0.55			
E	0.35	0.50			
F	5 DEG				
G	1.14	1.40			
Н	1.14	1.53			
К	12.70	_			
L	1.982	2.082			

All diminsions in mm.

TO-92 Plastic Package



TO-92 Transistors on Tape and Ammo Pack

All dimensions in mm unless specified otherwise

ITEM		SPECIFICATION		DEMARKS		
ITEM	SYMBOL	MIN.	NOM.	MAX.	TOL .	REMARKS
BODY WIDTH BODY HEIGHT BODY THICKNESS	A1 A T	4.0 4.8 3.9	10.7	4.8 5.2 4.2		
PITCH OF COMPONENT FEED HOLE PITCH FEED HOLF CENTRE TO	P Po		12.7 12.7		±1 ±0.3	CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH
COMPONENT CENTRE	P2		6.35		±0.4	TO BE MEASURED AT BOTTOM OF CLINCH
DISTANCE BETWEEN OUTER LEADS COMPONENT ALIGNMENT TAPE WIDTH HOLD-DOWN TAPE WIDTH HOLE POSITION	F △h Wo W1		5.08 0 18 6 9	1	+0.6 -0.2 ±0.5 ±0.2 +0.7 -0.5	AT TOP OF BODY
HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT COMPONENT HEIGHT LENGTH OF SNIPPED LEADS FEED HOLE DIAMETER TOTAL TAPE THICKNESS IFAD - TO - I FAD DISTANCFF1.	W2 Ho H1 L Do t F2		0.5 16 4 2.54	23.25 11.0 1.2	±0.2 ±0.5 ±0.2 +0.4	t1 0.3 - 0.6
CLINCH HEIGHT PULL - OUT FORCE	H2 (P)	6N	2.01	3	-0.1	

NOTES
1. MAXIMUM ALIGNMENT DEVIATION BETWEEN LEADS NOT TO BE GREATER THAN 0.2 mm.
2. MAXIMUM NON-CUMULATIVE VARIATION BETWEEN TAPE FEED HOLES SHALL NOT EXCEED 1 mm IN 20
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3.

HOLDDOWN TAPE NOT TO EXCEED BEYOND THE EDGE(S) OF CARRIER TAPE AND THERE SHALL BE NO HOLDDOWN TAPE NOT TO EXCEED BEYOND THE EDGE(S) OF CARRIER TAPE AND THERE SHALL BE NO EXPOSURE OF ADHESIVE. NO MORE THAN 3 CONSECUTIVE MISSING COMPONENTS ARE PERMITTED. A TAPE TRAILER, HAVING AT LEAST THREE FEED HOLES ARE REQUIRED AFTER THE LAST COMPONENT. SPLICES SHALL NOT INTERFERE WITH THE SPROCKET FEED HOLES.

4

5. 6.

Packing Detail

PACKAGE	STANDARD PACK		RD PACK INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	12.5 kgs

Notes

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TO-92 Plastic Package

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Discrete Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD is believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Discrete Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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Data Sheet